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CLAIMS

1. An organic electronic component with a spacing  $l$  between two conductor tracks, electrodes and/or between a conductor track and an electrode of less than  $10 \mu\text{m}$ , which has a substantially flat surface, that is to say the conductor track or tracks and/or the electrode or electrodes are raised less than  $300 \text{ nm}$  above the surface of a lower layer or the substrate.
2. An organic electronic component with a spacing  $l$  between two conductor tracks, electrodes and/or between a conductor track and an electrode of less than  $10 \mu\text{m}$ , wherein at least one conductor track and/or electrode is arranged in a recess of a lower layer, wherein the recess was produced by means of a layer, that is to say it has steep walls, sharp contours and a relatively rough bottom surface.
3. A process for the production of an organic electronic component in which to produce a conductor track and/or an electrode at least one recess is burnt into a lower layer or the substrate by means of laser and mask, wherein said recess has steep walls, sharp contours and a rough surface at the bottom, and in a subsequent process step is filled with conductive, predominantly organic material.
4. A process as set forth in claim 3 wherein the conductive material is scraped into the recess.
5. A process as set forth in one of claims 3 and 4 wherein excess conductive organic material is wiped away in a process step following the step of filling the recess with said material.
6. A process as set forth in one of claims 3 through 5 wherein a pulsed laser, for example an excimer laser is used.

7. A process as set forth in one of claims 3 through 6 which is performed in a continuous roll-to-roll procedure.
8. A process as set forth in claim 7 wherein the roller which wipes off the excess organic material rotates more slowly than the other rollers.